

ABSTRACT

A method and device are for anchoring fixed structural elements and, e.g., for anchoring electrodes for components, e.g., SOI wafer components, whose component structure is
5 formed in a silicon layer on top of a substrate used as support. The fixed element may be mechanically connected to the substrate via at least one anchoring element made of an anchoring material and extending through the silicon layer. In the case of an SOI wafer, the anchoring element may extend
10 through the silicon layer and the sacrificial layer of the SOI wafer. To this end, in the area of the surface of the fixed element, at least one recess is made in the silicon layer, which may extend through the entire silicon layer and the sacrificial layer down to the substrate. The recess may then
15 be filled with an anchoring material, so that the fixed element is mechanically connected to the substrate via the anchoring element that is thereby created.